

## Specifications

<i>Technology</i>	Stepper motor driven Y and Z axes Single board PC controller, menu programming
<i>Wire Types</i>	17.5 to 50 $\mu\text{m}$ diameter gold wire on 2" spool
<i>Bond Head</i>	Wire guide 90° wire feed Electronic touchdown sensing for every bond Programmable output ultrasonic system, 0 to 5 W, 60 kHz standard, other frequencies optional Programmable bond force 15 to 150 cN 16 mm capillaries can be used Conversion kit for fine and/or heavy wire wedge bonding
<i>Working Area</i>	Y axis: 50 mm, Z axis: 50 mm; 2.5 $\mu\text{m}$ / 1.25 $\mu\text{m}$ resolution Standard work height 136 mm (mid Z stroke) X/Y manipulator from 5x5 mm to 18x18 mm Equivalent manipulator step-down 1:2 to 1:7
<i>Work Holder</i>	Heated work holder with integrated digital temperature control up to 360°C Standard 60 mm $\varnothing$ for parts up to 2" x 2", mechanical clamping Optionally 80 mm $\varnothing$ and 4" x 4", mechanical and vacuum clamping
<i>Operating Modes</i>	Manual, semi-automatic, automatic, multi-wire Step mode for programme debug
<i>Loop Forms</i>	Standard rectangular, standard triangular, single and double reverse, stitch, ball-bumping
<i>Programme Memory</i>	Up to 50 individual wires per programme, 250 programmes per 3.5" floppy disk, can be edited and printed as text files via PC
<i>Dimensions</i>	Height 50 cm, width 60 cm, depth 60 cm, approx. 55 kg
<i>Supplies</i>	100 to 230 VAC, single-phase; air/vacuum 6 mm $\varnothing$ connector if necessary



# 5410

## Manual and Semi-automatic Gold Ball Bonder

The 5410 is used around the world for small-scale production at R&D institutes and laboratories and for low or pre-production lots of COB and substrates. Flexibility and optimum quality for complex applications make it the bonder of choice. Parameters for individual wires can be programmed and saved on a floppy disk enabling bonding with repeatable results every time. Stepping motor driven Y and Z axes allow single or multiple bonds to be made reliable and repeatable under full programme control. Operators and programmers require only minimum training ensuring rapid return on investment

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